

Electronic Acknowledgement Receipt

EFS ID:	1060928
Application Number:	10596114
Confirmation Number:	2228
Title of Invention:	RESIN COMPOSITION, MOLDED PRODUCT FROM RESIN COMPOSITION AND METHOD FOR PREPARING RESIN COMPOSITION
First Named Inventor:	Takeshi Horie
Customer Number:	26263
Filer:	David Richard Metzger/Barbara Hannon
Filer Authorized By:	David Richard Metzger
Attorney Docket Number:	09792909-6708
Receipt Date:	31-MAY-2006
Filing Date:	
Time Stamp:	14:52:59
Application Type:	U.S. National Stage under 35 USC 371
International Application Number:	PCT/JP04/17728

Payment information:

Submitted with Payment	yes
Payment was successfully received in RAM	\$3950
RAM confirmation Number	20
Deposit Account	

File Listing:

Document Number	Document Description	File Name	File Size(Bytes)	Multi Part	Pages
-----------------	----------------------	-----------	------------------	------------	-------

1		Sony_6708_Spec.pdf	334910	yes	110
	Multipart Description				
	Doc Desc		Start	End	
	Specification		1	102	
	Claims		103	109	
	Abstract		110	110	
Warnings:					
Information:					
2	Documents submitted with 371 Applications	Sony_6708_PCT_Req.pdf	155499	no	6
Warnings:					
Information:					
3	NPL Documents	Sony_6708_IDS_ISR.PDF	77571	no	2
Warnings:					
Information:					
4	Oath or Declaration filed	Sony_6708_Dec.pdf	192338	no	4
Warnings:					
Information:					
5	Foreign Reference	Sony_6708_IDS_Ref1.pdf	873971	no	16
Warnings:					
Information:					
6	Foreign Reference	Sony_6708_IDS_Ref2.pdf	906080	no	16
Warnings:					
Information:					
7	Foreign Reference	Sony_6708_IDS_Ref3.pdf	748842	no	13
Warnings:					
Information:					

8	Foreign Reference	Sony_6708_IDS_Ref4.pdf	296257	no	8
Warnings:					
Information:					
9	Foreign Reference	Sony_6708_IDS_Ref5.pdf	939826	no	16
Warnings:					
Information:					
10	Foreign Reference	Sony_6708_IDS_Ref6.pdf	598281	no	11
Warnings:					
Information:					
11	Information Disclosure Statement (IDS) Filed	Sony_6708_US_IDS_Form_SB_08a.pdf	870628	no	4
Warnings:					
Information:					
<p>A U.S. Patent Number Citation or a U.S. Publication Number Citation is required in the Information Disclosure Statement (IDS) form for autoloading of data into USPTO systems. You may remove the form to add the required data in order to correct the Informational Message if you are citing U.S. References. If you chose not to include U.S. References, the image of the form will be processed and be made available within the Image File Wrapper (IFW) system. However, no data will be extracted from this form. Any additional data such as Foreign Patent Documents or Non Patent Literature will be manually reviewed and keyed into USPTO systems.</p>					
12	Information Disclosure Statement (IDS) Filed	Sony_6708_IDS.pdf	67699	no	1
Warnings:					
Information:					
This is not an USPTO supplied IDS fillable form					
13	Documents submitted with 371 Applications	Sony_6708_Req_Exam.pdf	64690	no	1
Warnings:					
Information:					
14	Fee Worksheet (PTO-875)	fee-info.pdf	8615	no	2
Warnings:					
Information:					
Total Files Size (in bytes):			6135207		

This Acknowledgement Receipt evidences receipt on the noted date by the USPTO of the indicated documents, characterized by the applicant, and including page counts, where applicable. It serves as evidence of receipt similar to a Post Card, as described in MPEP 503.

New Applications Under 35 U.S.C. 111

If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

National Stage of an International Application under 35 U.S.C. 371

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.